

## Wencon Test Methods

All Wencon Epoxy products are tested according to below mentioned methods. Only the test, important for calculation of which product to choose for which application, are mentioned below:

1. All tests are with the exception of the determination of the heat resistance, executed at room temperature 20°C (68°F).
2. The potlife and "highest temperature during reaction" are determined with 100 grams mixed material. The rise of temperature is measured with the aid of a digital thermometer.
3. For the determination of the heat resistance, the products are coated on steel plates and stored during seven days at room temperature. After those seven days they are stored at elevated temperature and reviewed every 24 hours.
4. Compressive strength:
  - curing time: 14 days
  - dimensions of the cubes: 13 x 13 x 13 mm
  - used testing machine: Wolpert, type TT 1220 25 kN
  - testing speed: 5 mm / min

Modulus of elasticity: A calculated factor showing the relationship between the press on the material and the defomation.

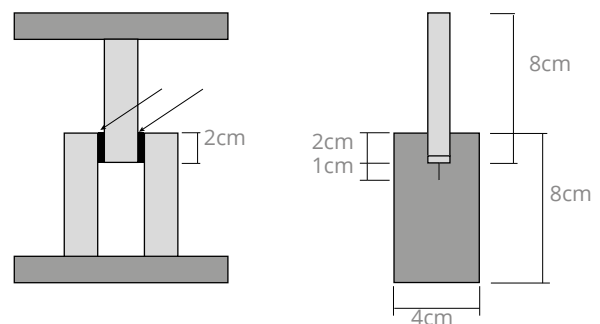
R crack : The point where the material breaks apart

5. Tensile strength:
  - Curing time: 14 days
  - used testing machine: Wolpert, type TT 1220 25 kN
  - Testing speed: 15 mm / min

Modulus of elasticity: A calculated factor showing the relationship between the press on the material and the defomation.

R crack : The point where the material breaks apart

6. Shear adhesion to steel: The shear adhesion is determined according to the subjoined illustration



The test bars are sandblasted to optimise the adhesion of the applied Wencon product. After the surfaces were glued together with the several Wencon products, they are cured seven days at room temperature.

The shear adhesion is determined using the following testing machine: Wolpert, type TT 1220 25 kN. The shear adhesion is calculated according to following formula:

$$X = P / A$$

X: shear adhesion (N/mm<sup>2</sup>)

P: pressure at break (N)

A: total of the glued area (mm<sup>2</sup>)